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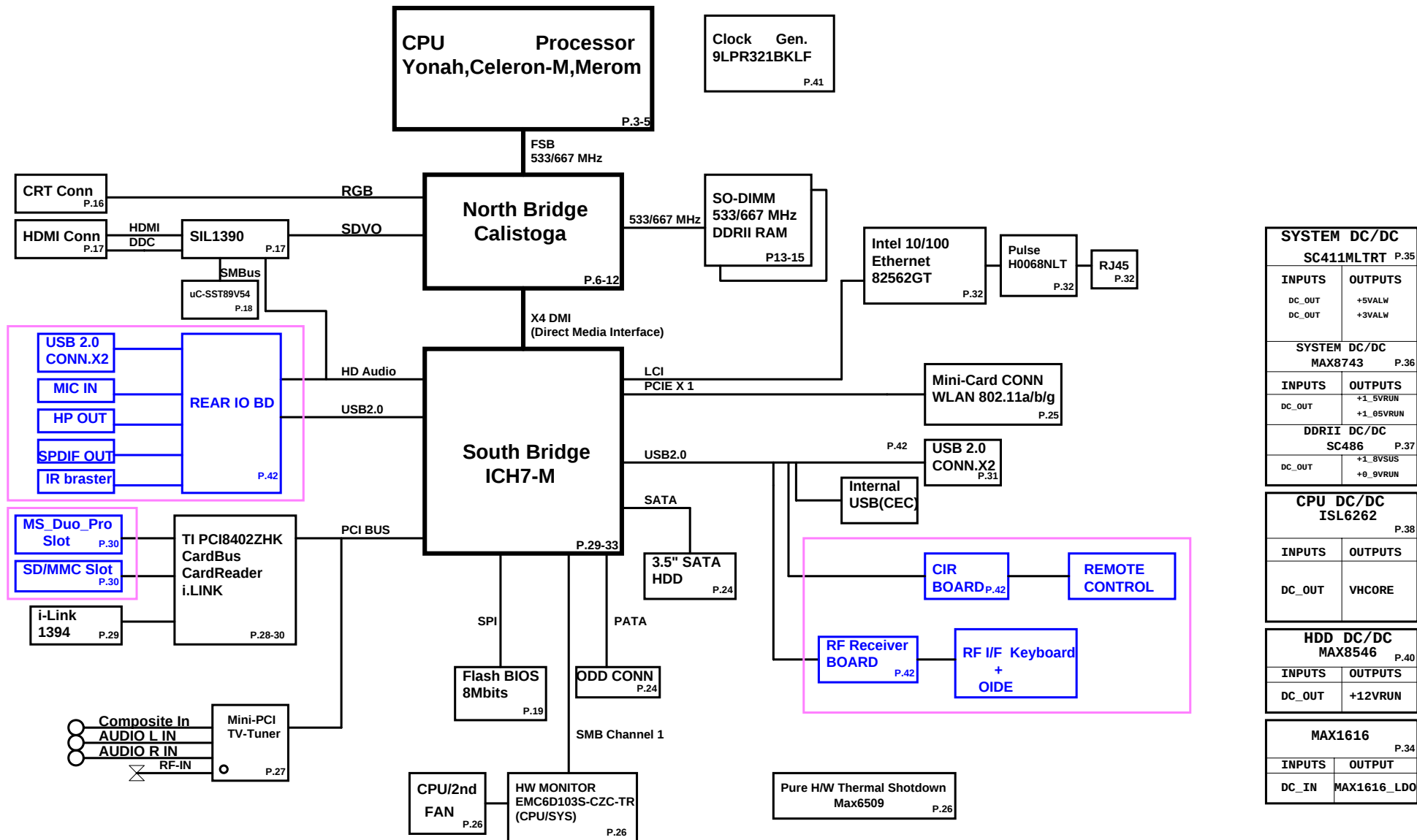
P. Leader	Check by	Design by

PCB P/N: 1P-106A100-40SB

Project Code & Schematics Subject: MS80 Main Board

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MS80 Bolck diagram

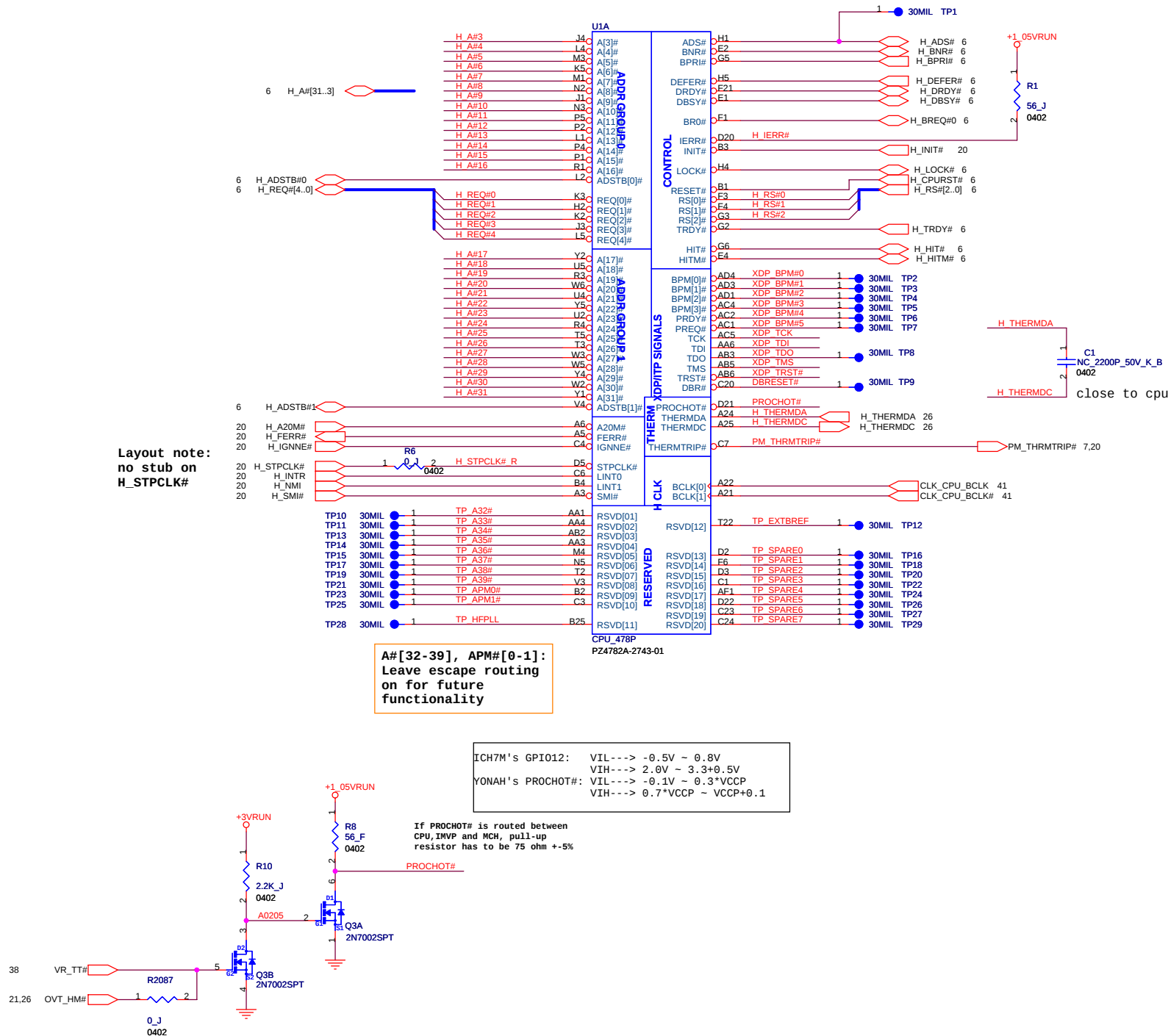


Layout note:
no stub on
H_STPCLK#

A#[32-39], APM#[0-1]:
Leave escape routing
on for future
functionality

ICH7M's GPIO12: VIL --- -0.5V ~ 0.8V
VIH --- 2.0V ~ 3.3+0.5V
YONAH's PROCHOT#: VIL --- -0.1V ~ 0.3*VCCP
VIH --- 0.7*VCCP ~ VCCP+0.1

If PROCHOT# is routed between
CPU, IMVP and MCH, pull-up
resistor has to be 75 ohm +-5%



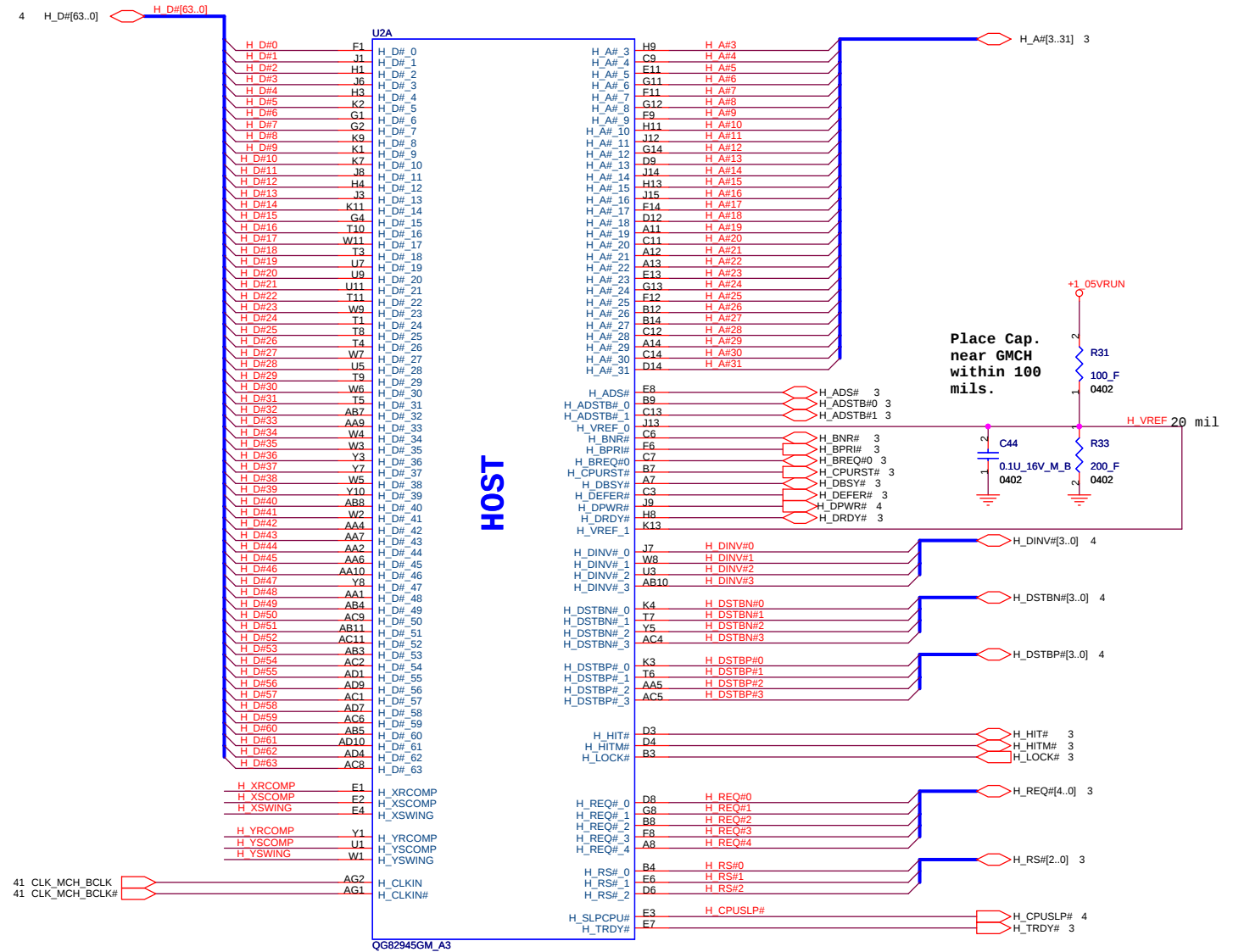
Place close to CPU

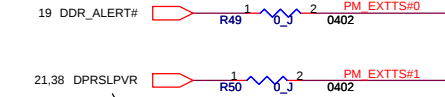
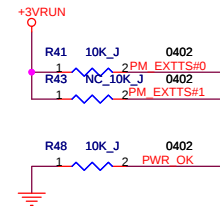
Layout Note:
Zo=55 ohm, 0.5"
max for GTLREF.

FSB Frequency Table:

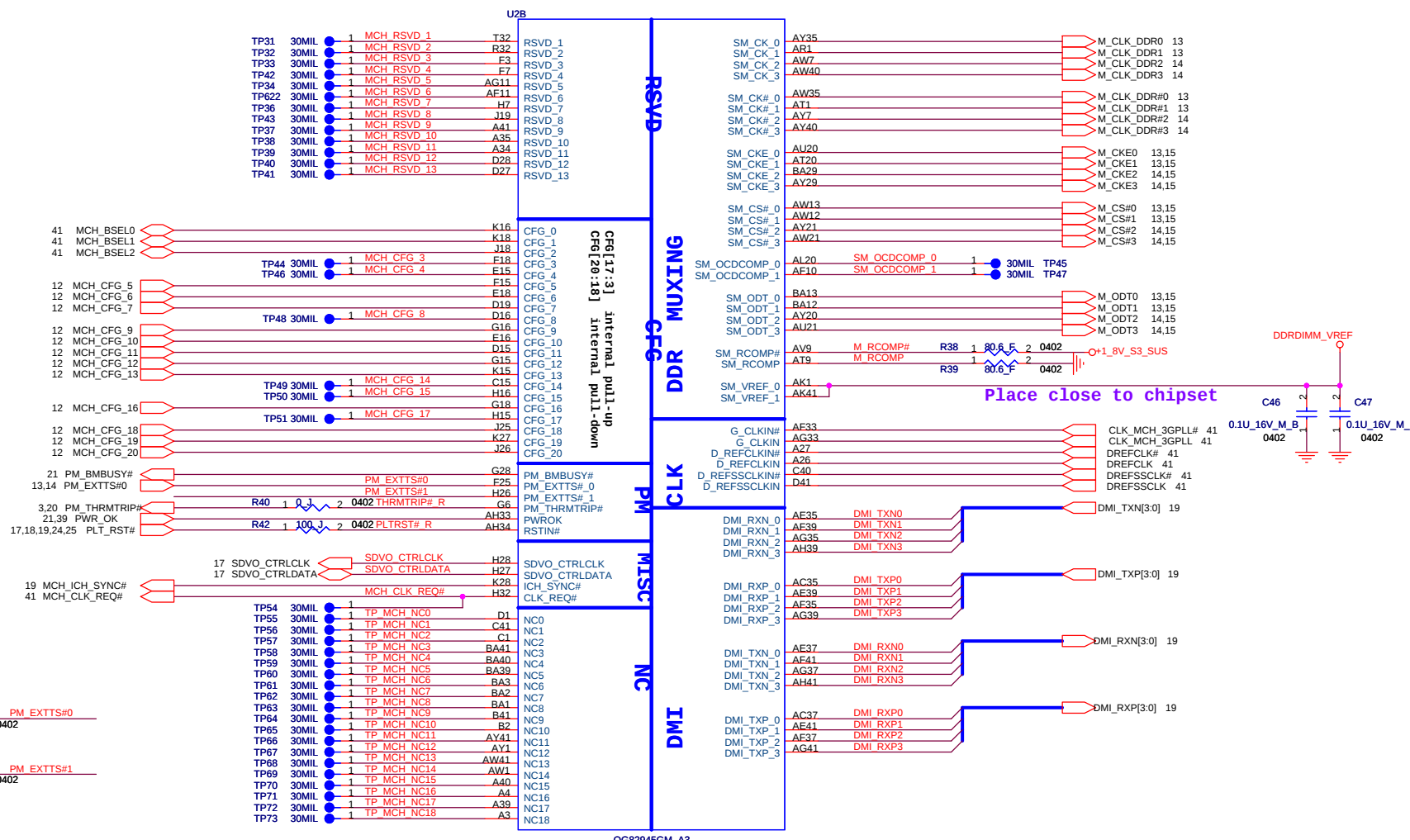
BSEL[2:0]	Freq.(MHz)
L L L	Reserve
L L H	133
L H L	Reserve
L H H	166

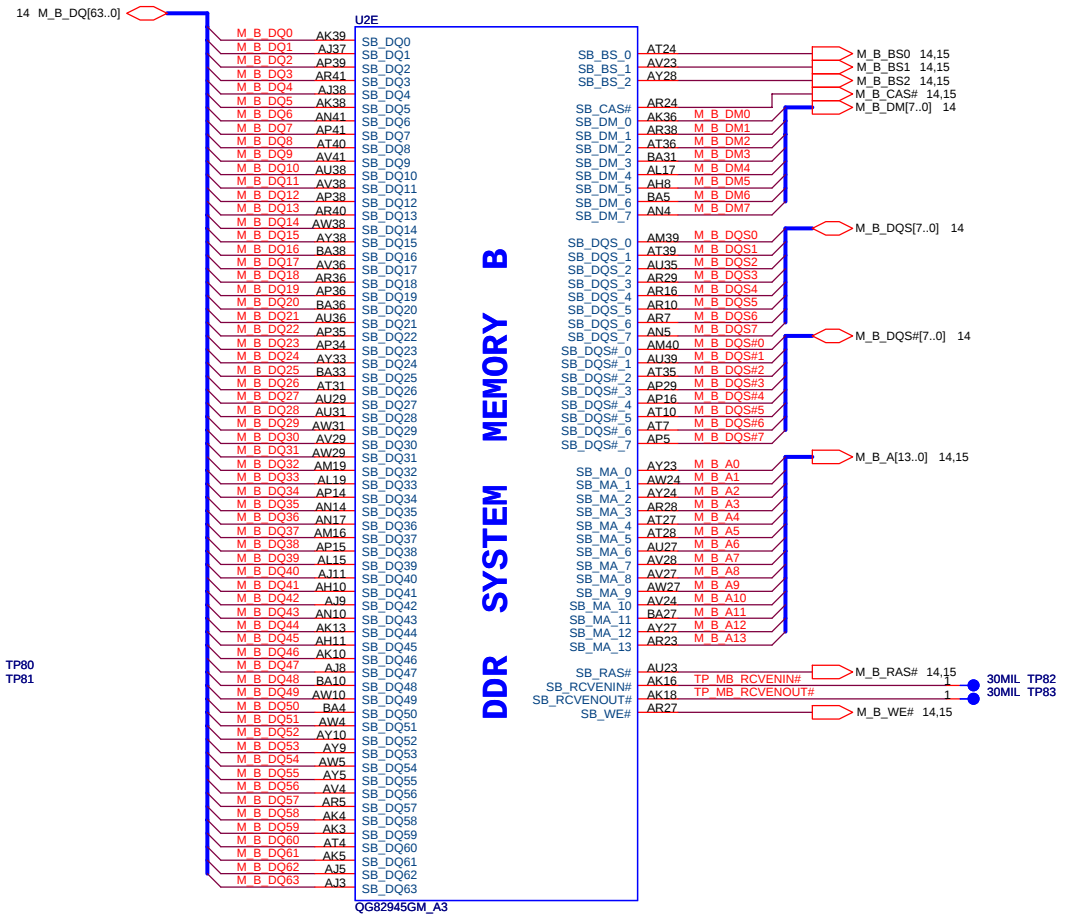
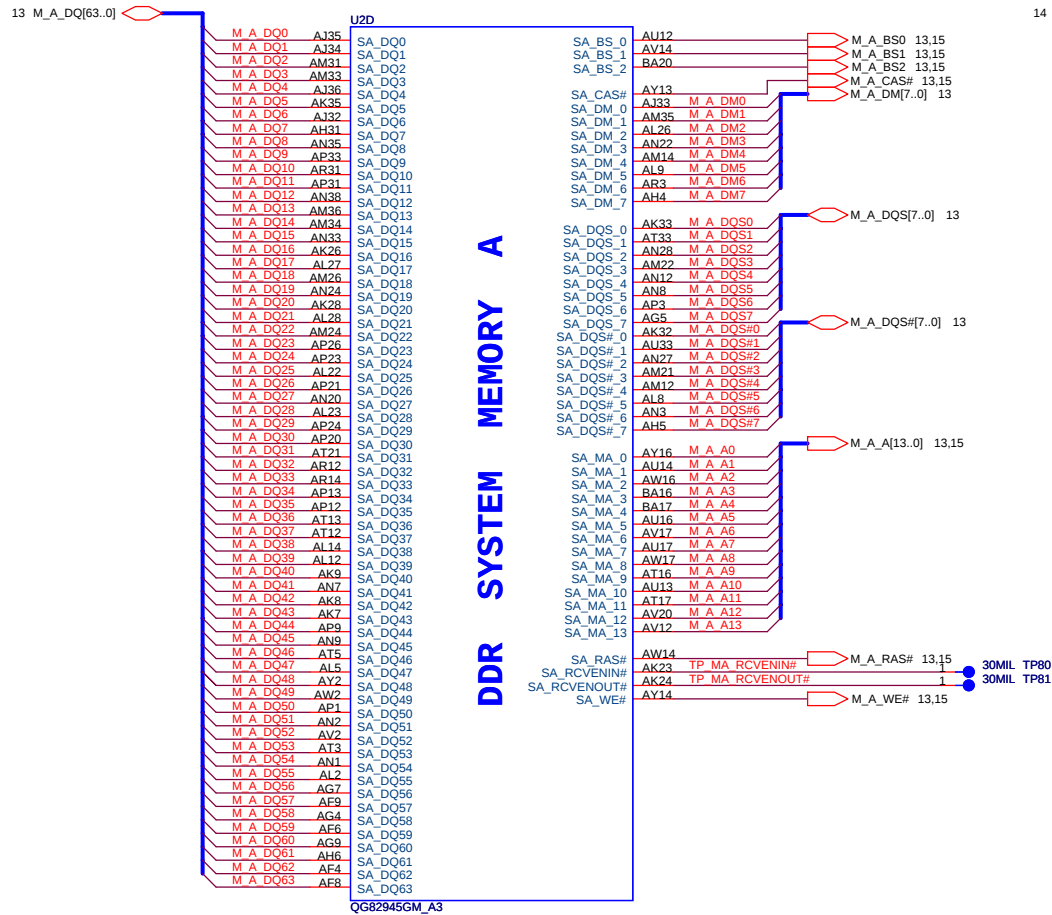
Layout Note:
Comp0,2 connect with Zo=27.4 ohm, make
trace length shorter then 0.5".
Comp1,3 connect with Zo=55 ohm, make
trace length shorter then 0.5".

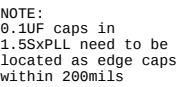




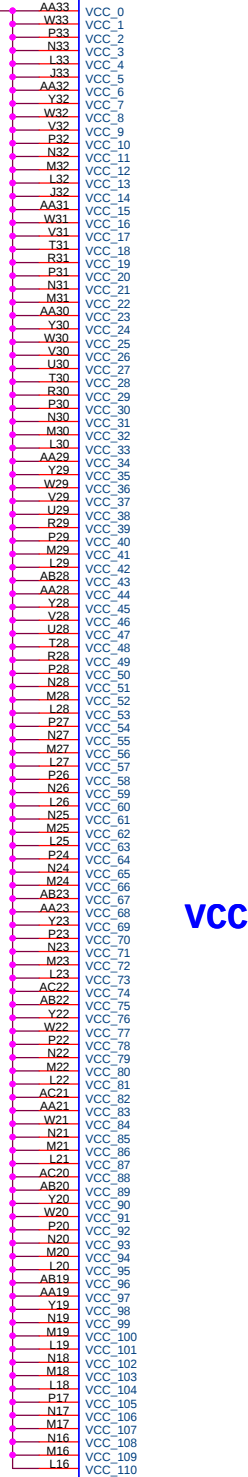
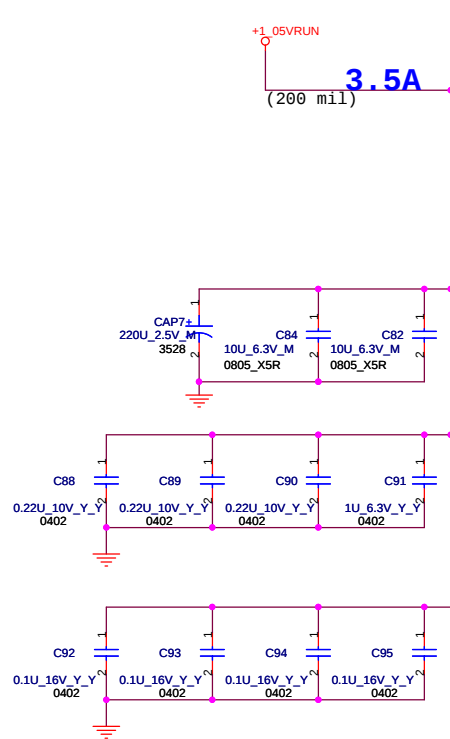
CRB rev:1.301 update



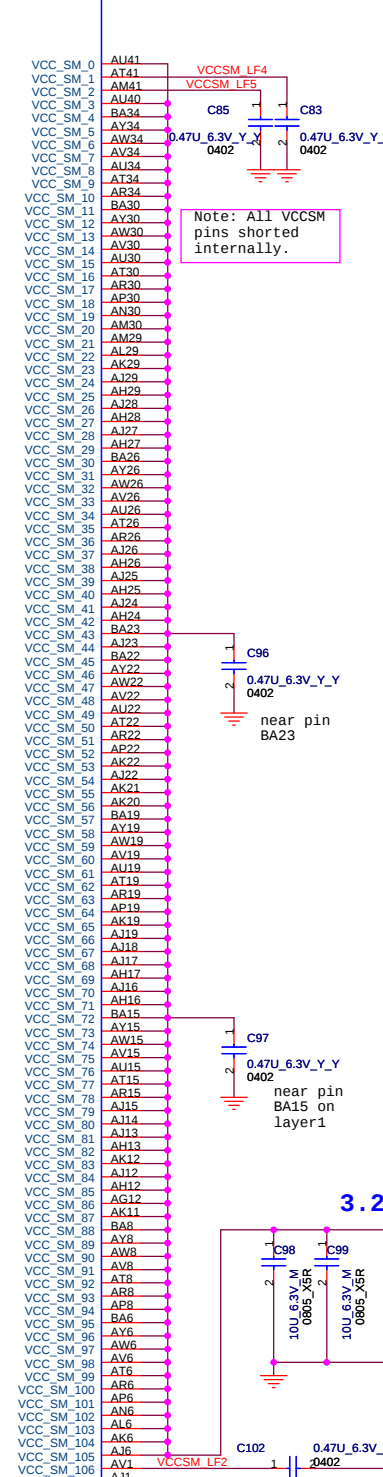




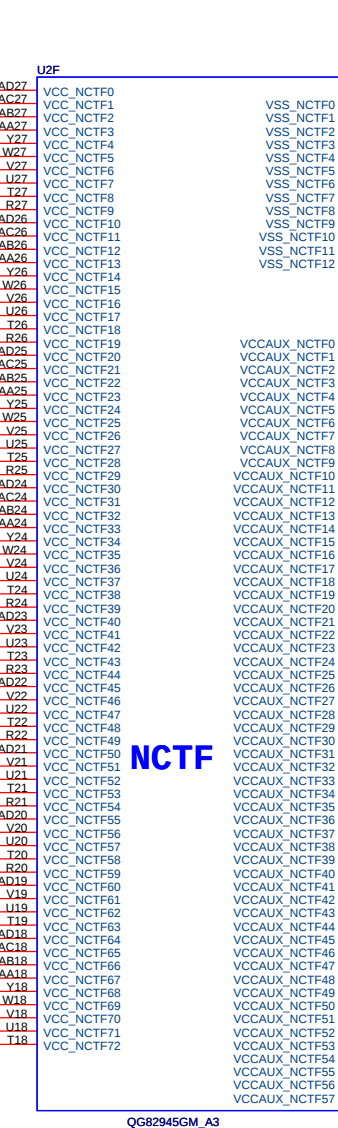
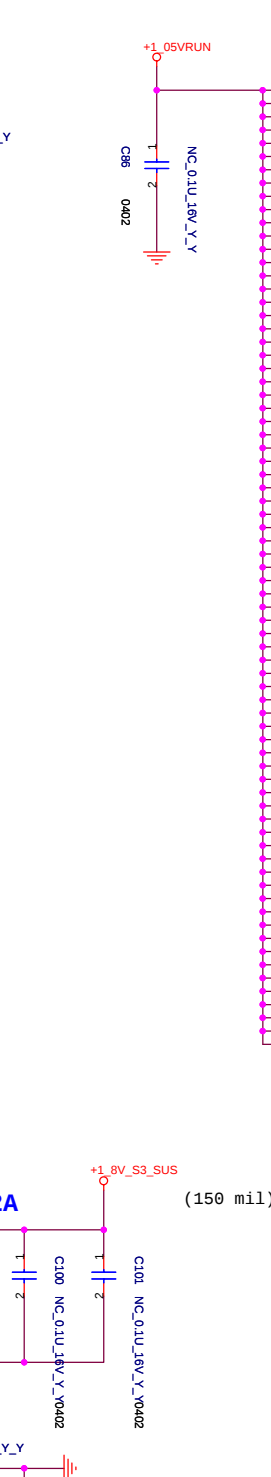
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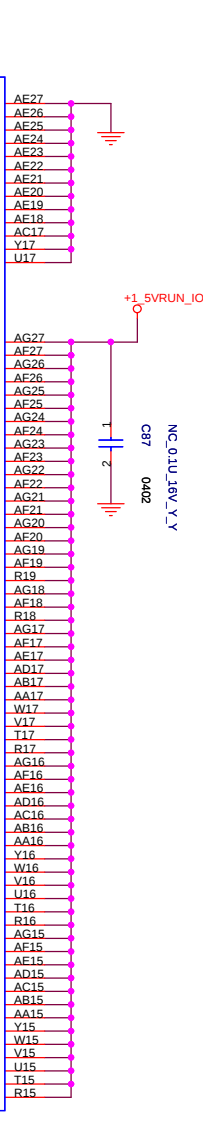
VCC



Note: All VCCSM pins shorted internally.



NCTF



7 MCH_CFG_5 ◀ 1 ● 30MIL TP84

MCH_CFG_5
Low = DMIX2
High = DMIX4

7 MCH_CFG_6 ◀ 1 ● 30MIL TP85

MCH_CFG_6
Low = Moby Dick
High = Calistoga
DDR2 select (default high)

7 MCH_CFG_7 ◀ 1 ● 30MIL TP87

MCH_CFG_7
(CPU Strap)
Low = RSVD
High = Mobile Yonah processor

7 MCH_CFG_9 ◀ 1 ● 30MIL TP89

MCH_CFG_9
(PCIe Graphics Lane)
Low = Reverse Lane
High = Normal operation

For layout convenience

7 MCH_CFG_10 ◀ 1 ● 30MIL TP90

MCH_CFG_10
(HOST PLL VCC SELECT)
Low = RESERVED
High = MOBILITY

7 MCH_CFG_11 ◀ 1 ● 30MIL TP91

MCH_CFG_11
(PSB 4x CLK ENABLE)
Low = Reserved
High = Calistoga



7 MCH_CFG_12 ◀ 1 ● 30MIL TP92

7 MCH_CFG_13 ◀ 1 ● 30MIL TP93

MCH_CFG_13[13:12]
(XOR/ALLZ)
00=Partial Clock Gating Disable
01=XOR Mode Enable
10=All-Z Mode Enable
11=Normal Operation(Default)

7 MCH_CFG_16 ◀ 1 ● 30MIL TP94

MCH_CFG_16
(FSB Dynamic ODT)
Low = Dynamic ODT Disabled
High = Dynamic ODT Enable

MCH_CFG_18
(VCC_CORE Select)
Low = 1.05V(default)
High = 1.5V

7 MCH_CFG_18 ◀ 1 ● 30MIL TP86

MCH_CFG_19
(DMI LANE REVERSAL)
Low = Normal(default)
High = LANES REVERSED

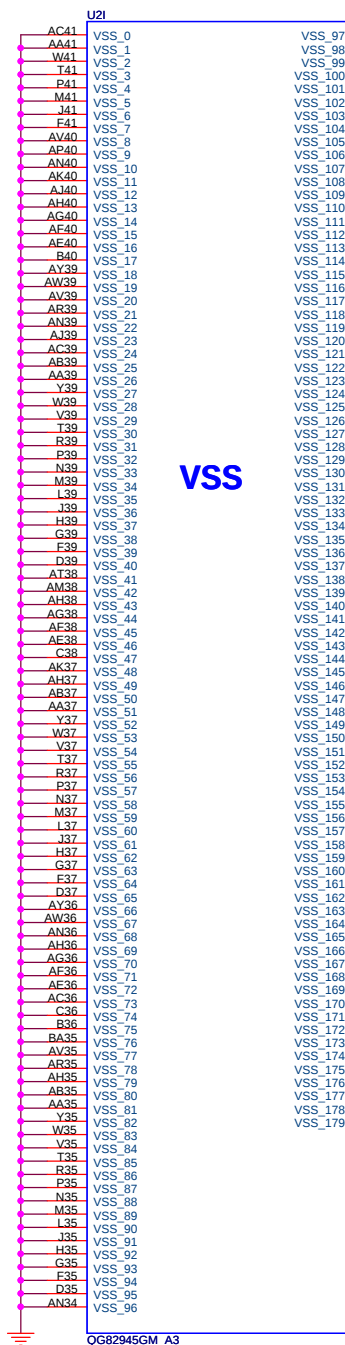
7 MCH_CFG_19 ◀ 1 ● 30MIL TP88

MCH_CFG_20
(PCIe Backward Interoperability mode)
Low = Only SDVO or PCIe x1 is operational (defaults)
High = SDVO and PCIe x1 are operating simultaneously via the PEG port

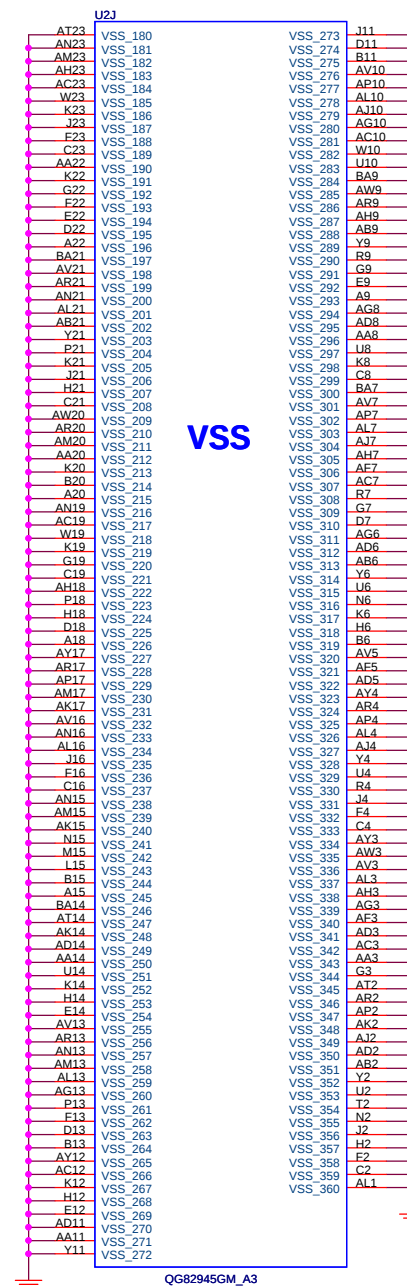
7 MCH_CFG_20 ◀ 1 ● 30MIL TP91

Layout Noe:
Location of all MCH_CFG strap resistors needs to be close to trace to minimize stub

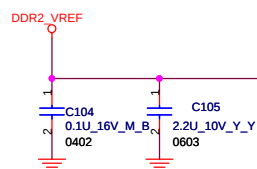
Check CALISTOGA version , after A2 version , if systec can't boot up then NC the pull low R



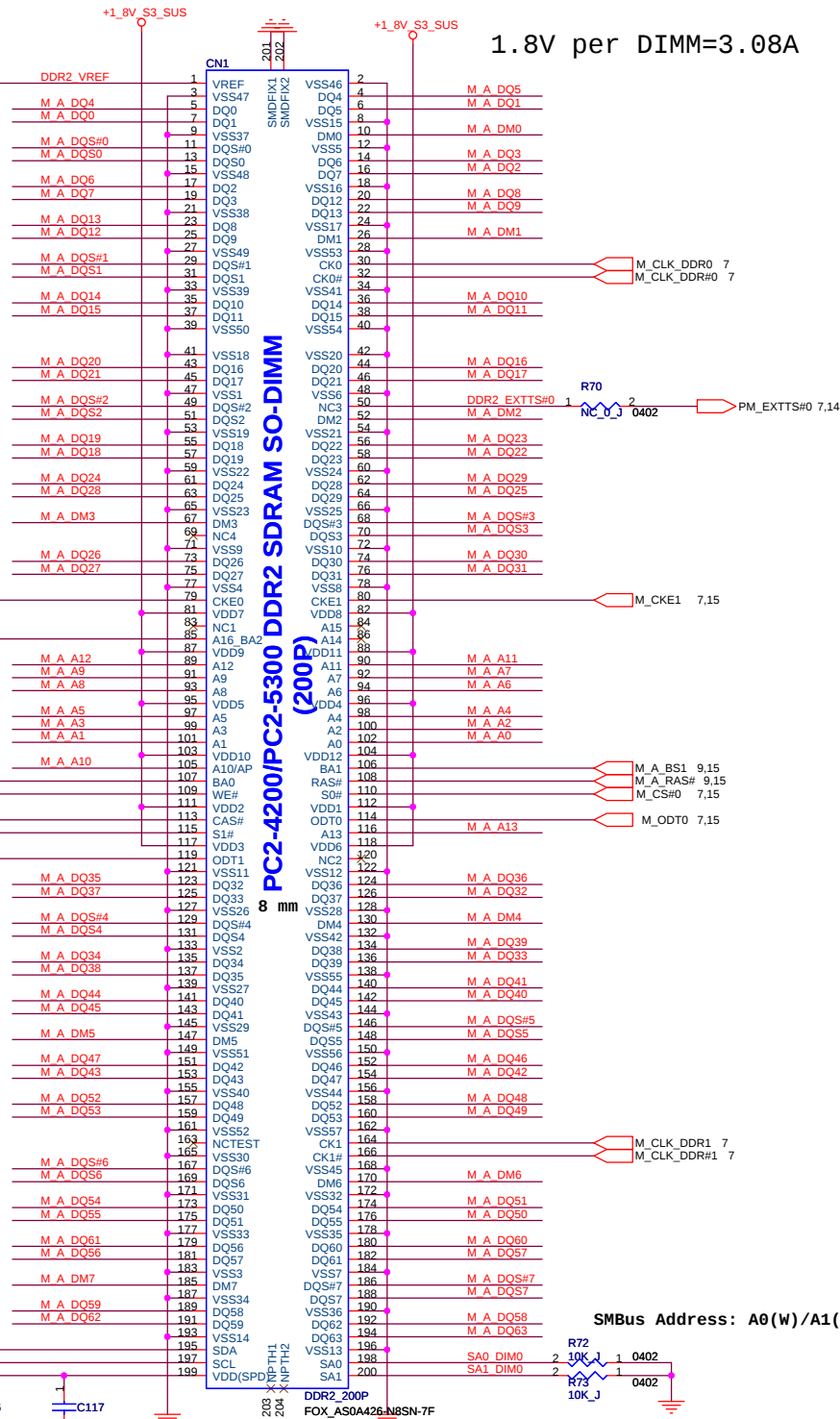
VSS



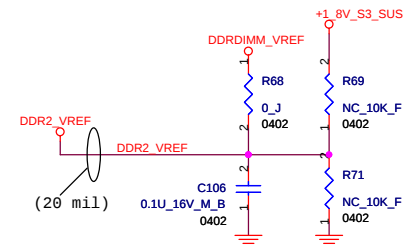
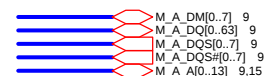
VSS



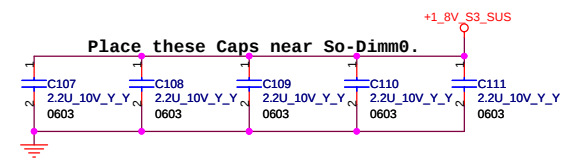
0.1 μ F and 2.2 μ F placed close to VREF pins



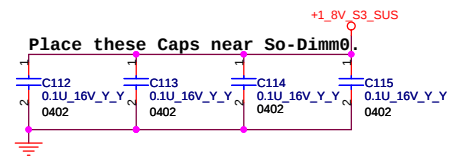
1.8V per DIMM=3.08A



Close to DIMM



Place these Caps near So-Dimm0.

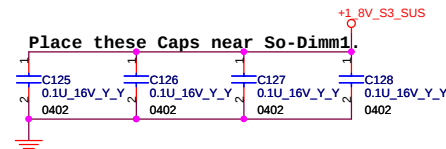
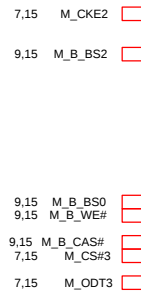
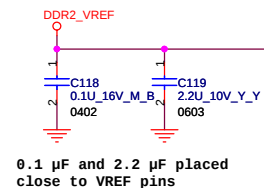


Place these Caps near So-Dimm0.

SMBus Address: A0(W)/A1(R)

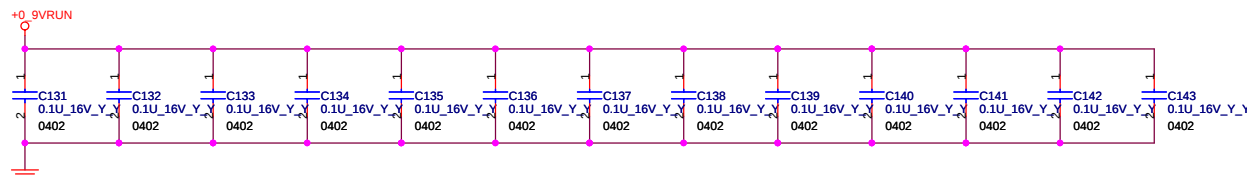
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Title DDR(II)SO-DIMM_0	
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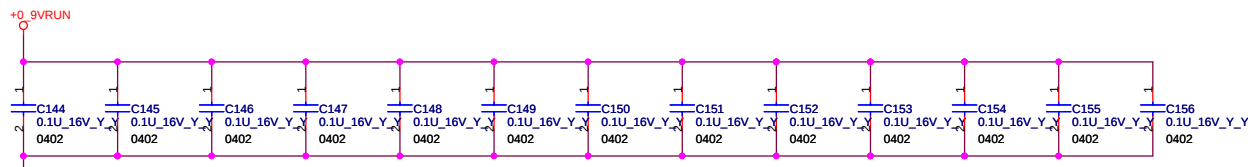


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Title	DDR(II)SO-DIMM_1	
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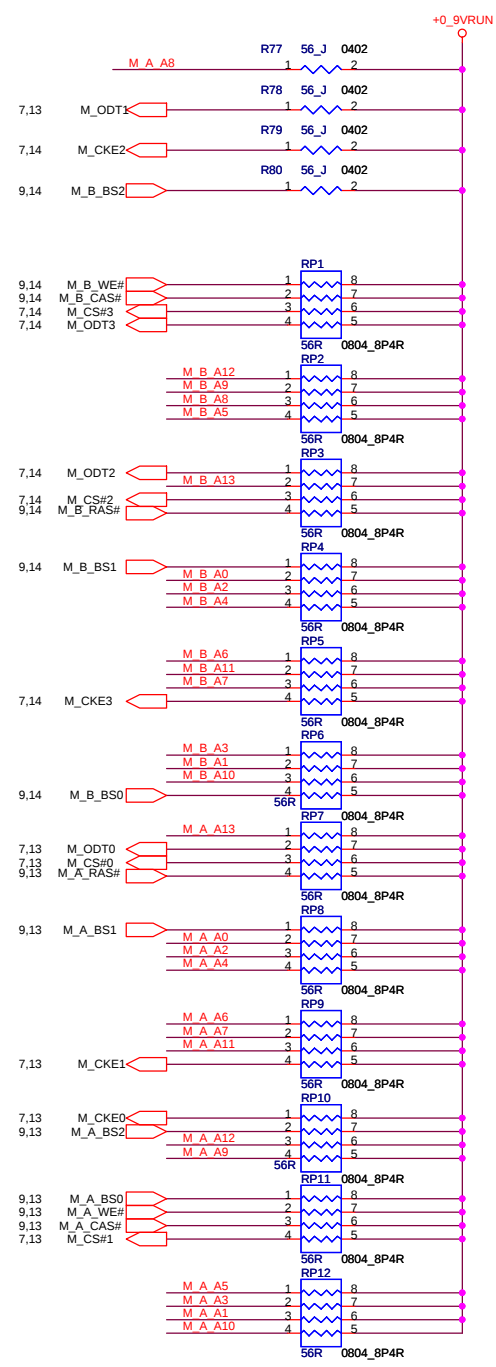
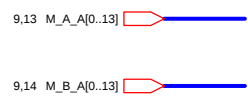
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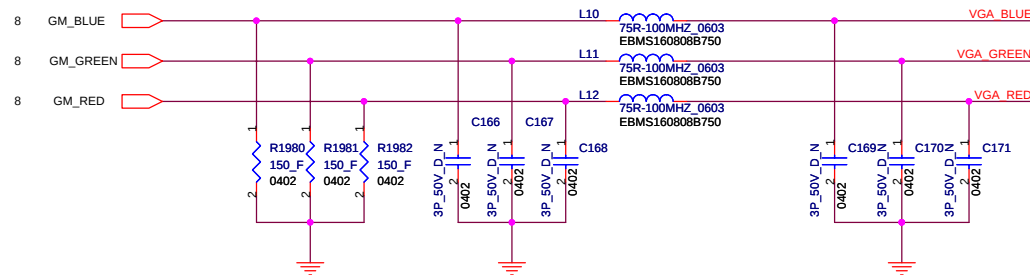
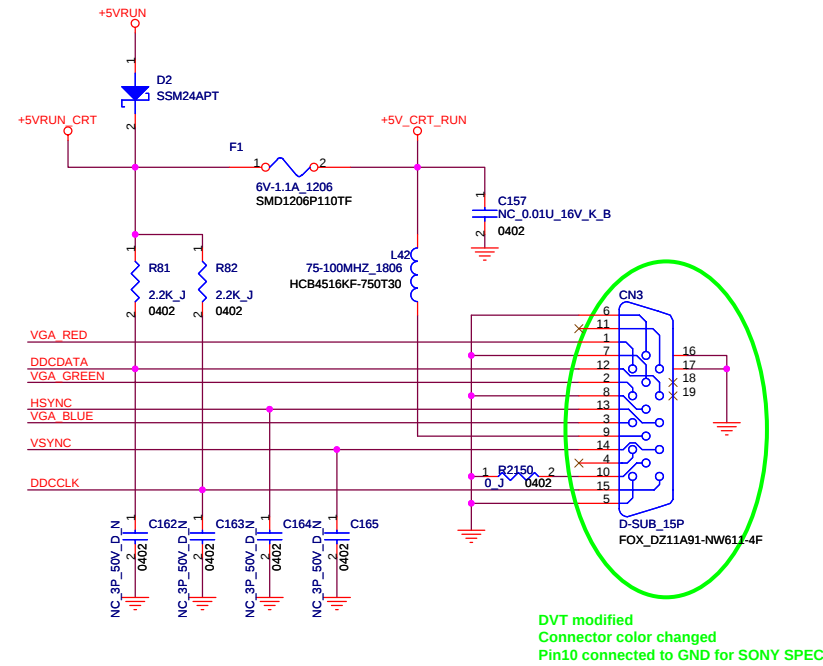
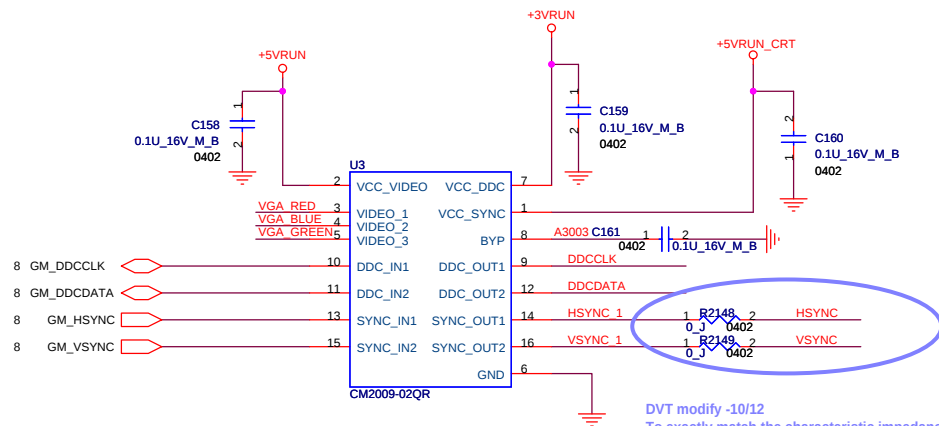


Layout note: Place 1 cap close to every 1 R-pack terminated to +0_9VRUN

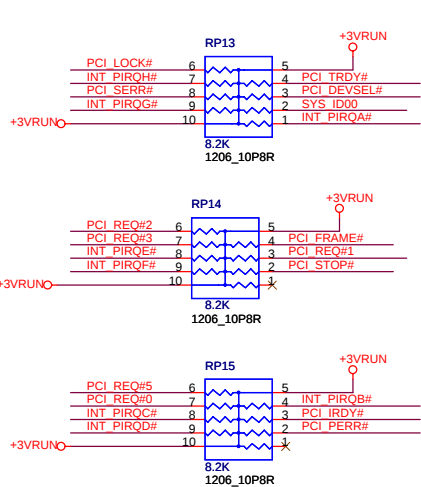


Layout note: Place 1 cap close to every 1 R-pack terminated to +0_9VRUN



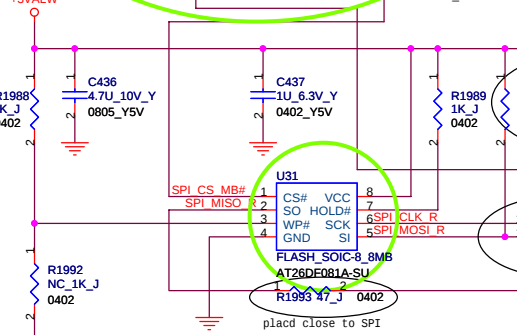
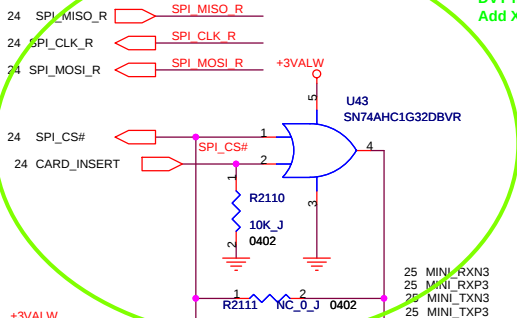




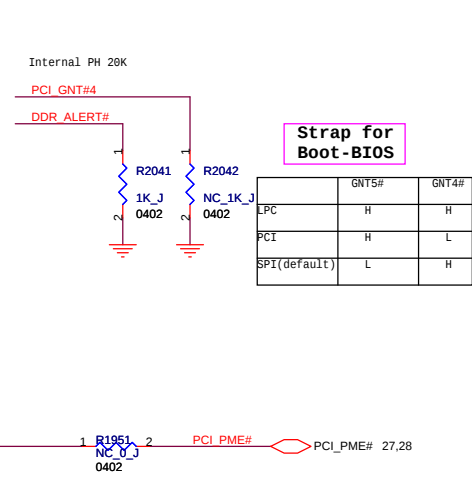
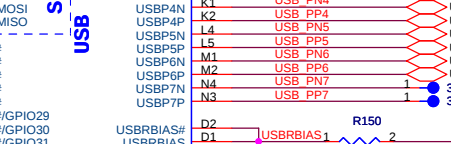
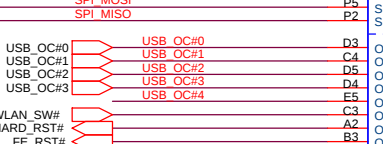
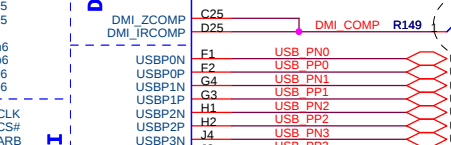
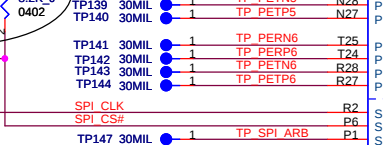
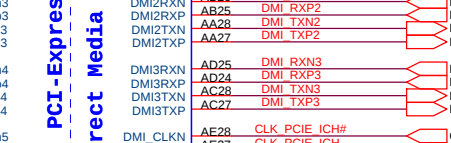
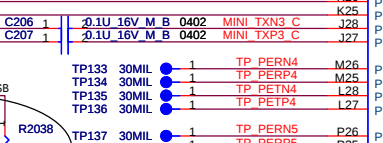
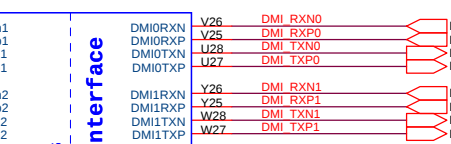
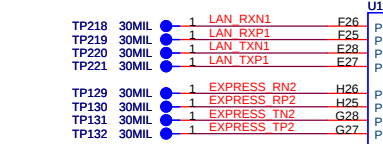
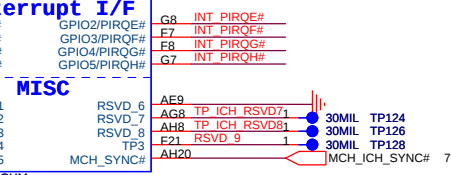
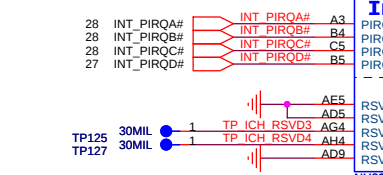
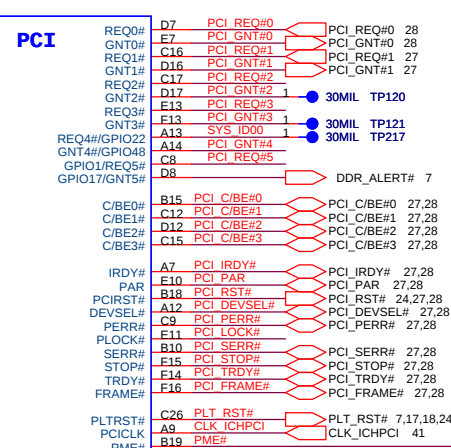
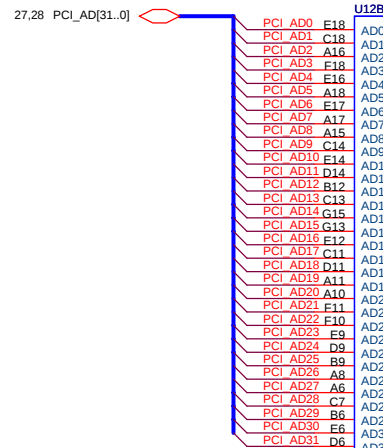
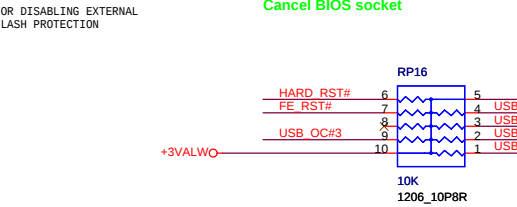


PCI Pullups

DVT modified
Add X-BUS function



DVT modified
Cancel BIOS socket



Test leakage voltage in BB

Test leakage voltage in BB

Test leakage voltage in BB

Test leakage voltage in BB

Test leakage voltage in BB

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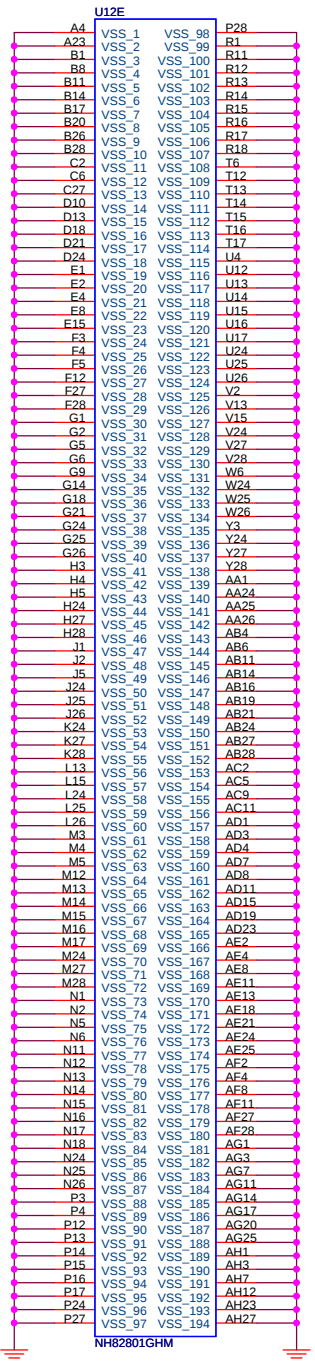
Test leakage voltage in BB

Test leakage voltage in BB

Test leakage voltage in BB

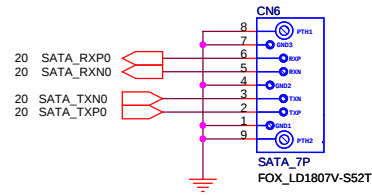




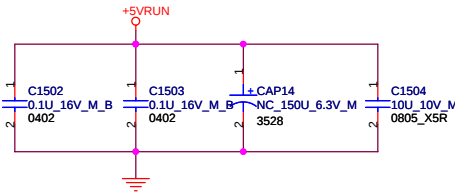
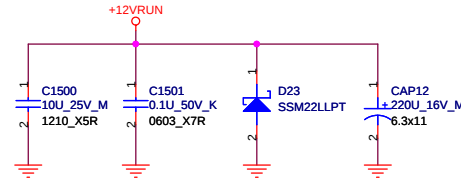
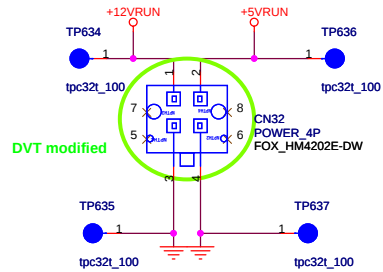


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Title ICH7-M(GND) 5/5	
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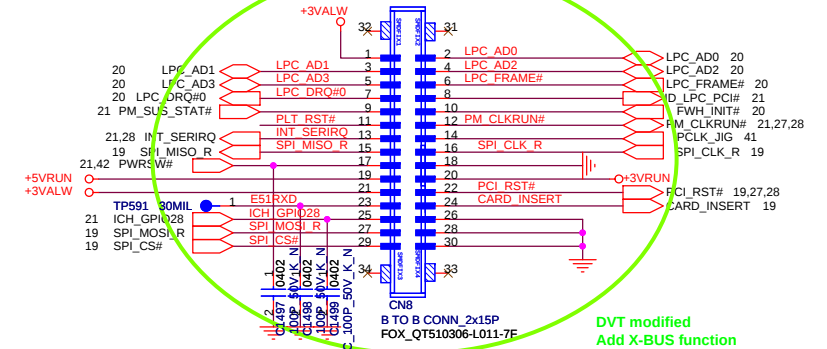
SATA HDD CONN



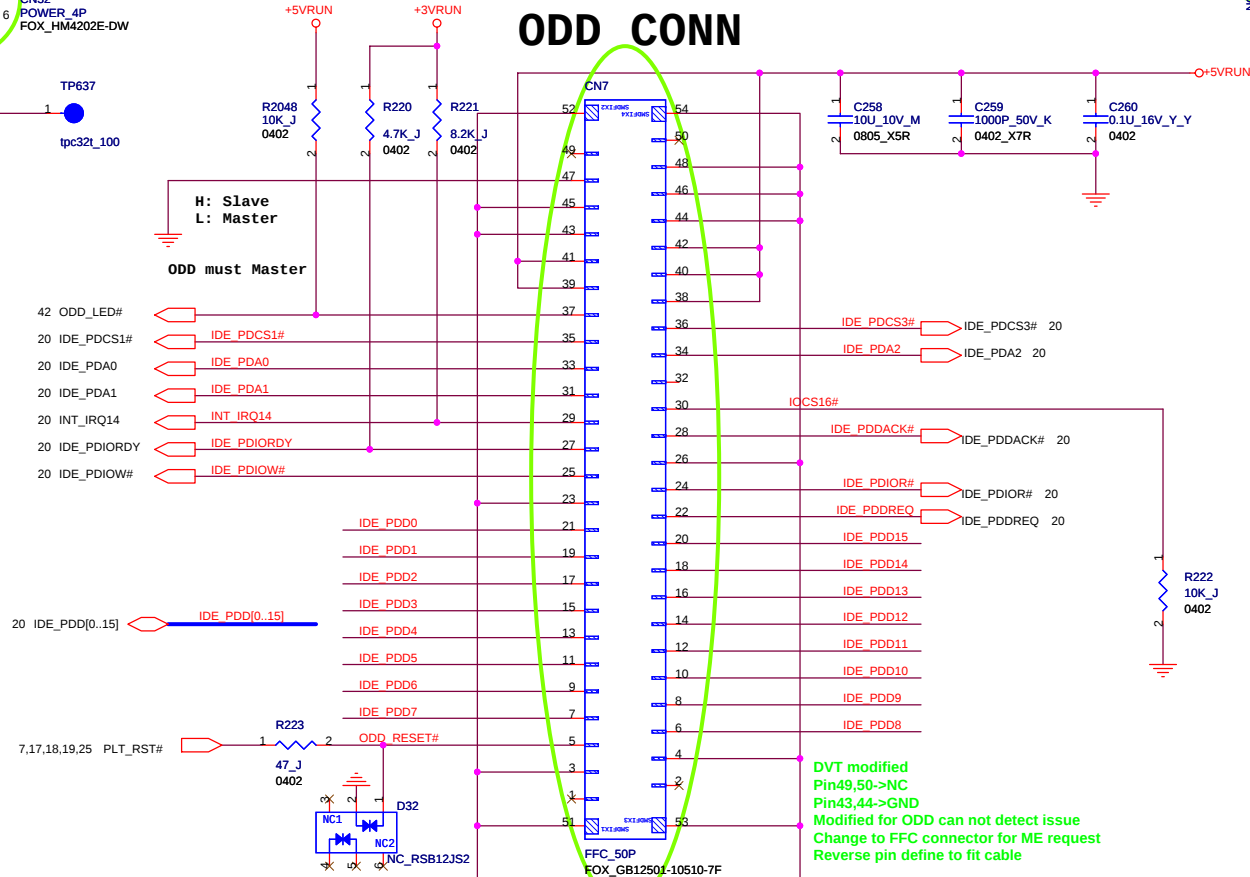
SATA HDD PWR



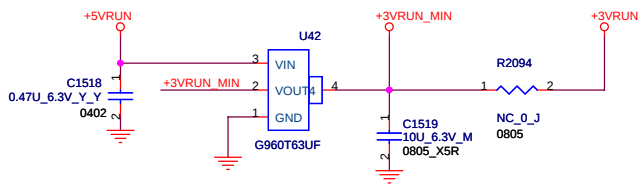
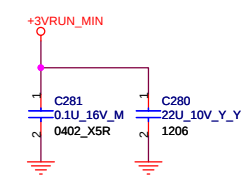
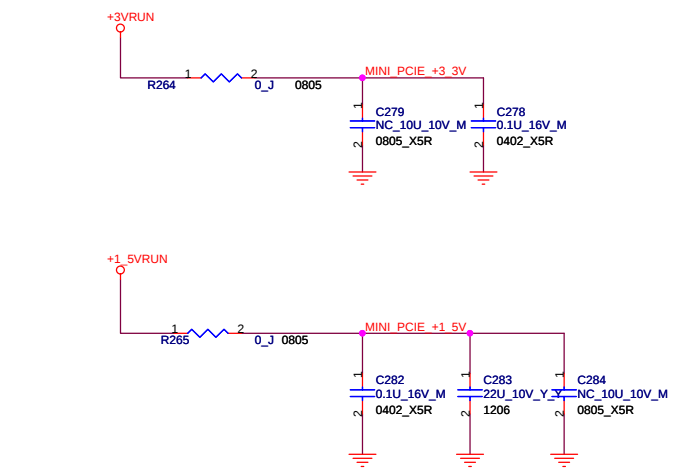
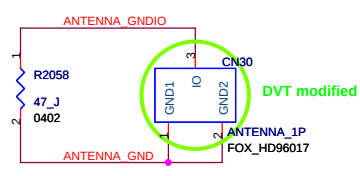
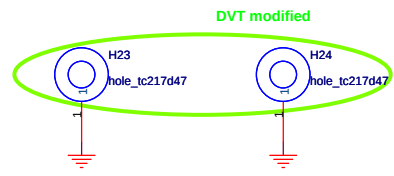
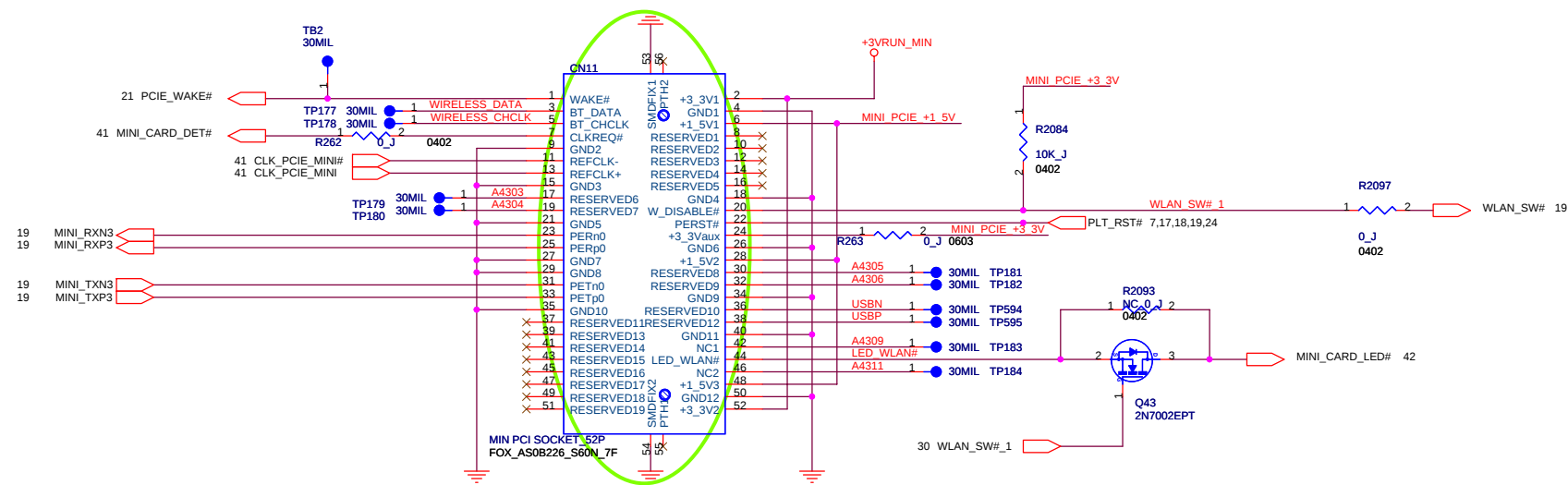
JIG-120



ODD CONN



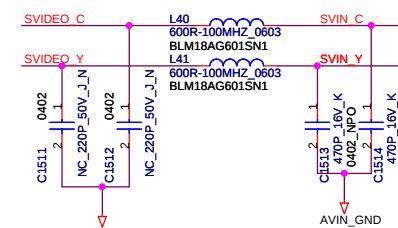
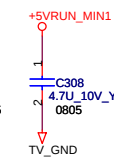
FOXCONN HON HAI PRECISION IND. CO., LTD.			
CPBG - R&D Division			
Title			
SATA HDD/CD-ROM/DEBUGPORT			
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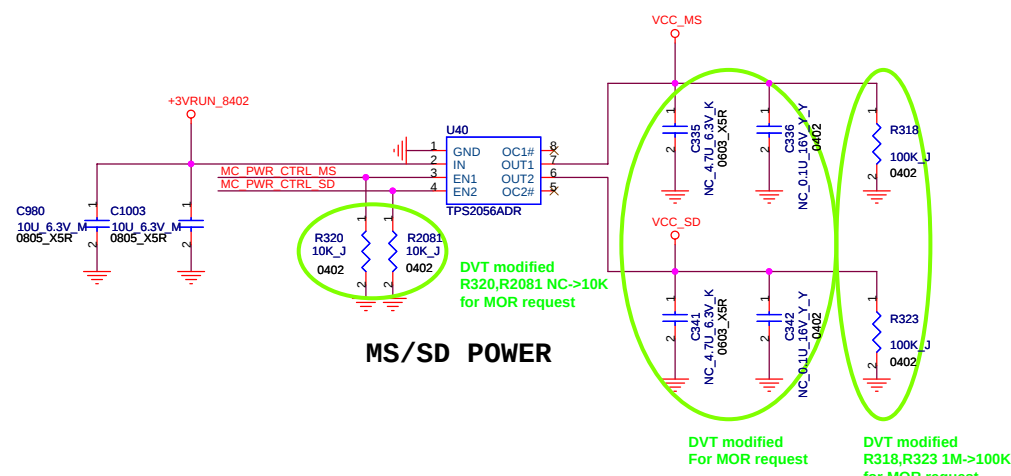
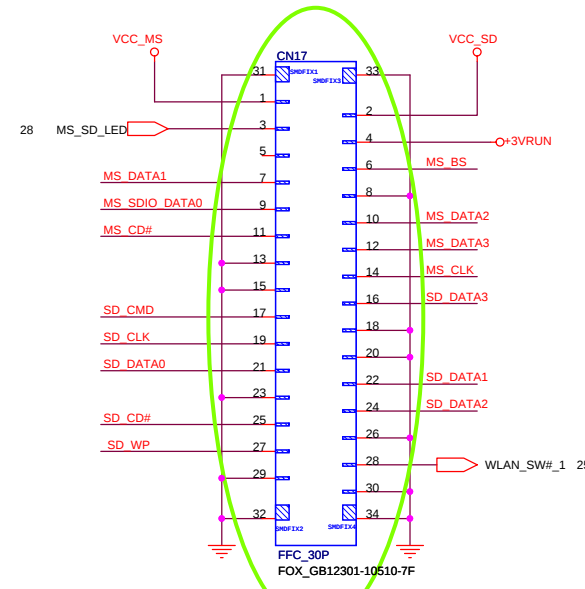
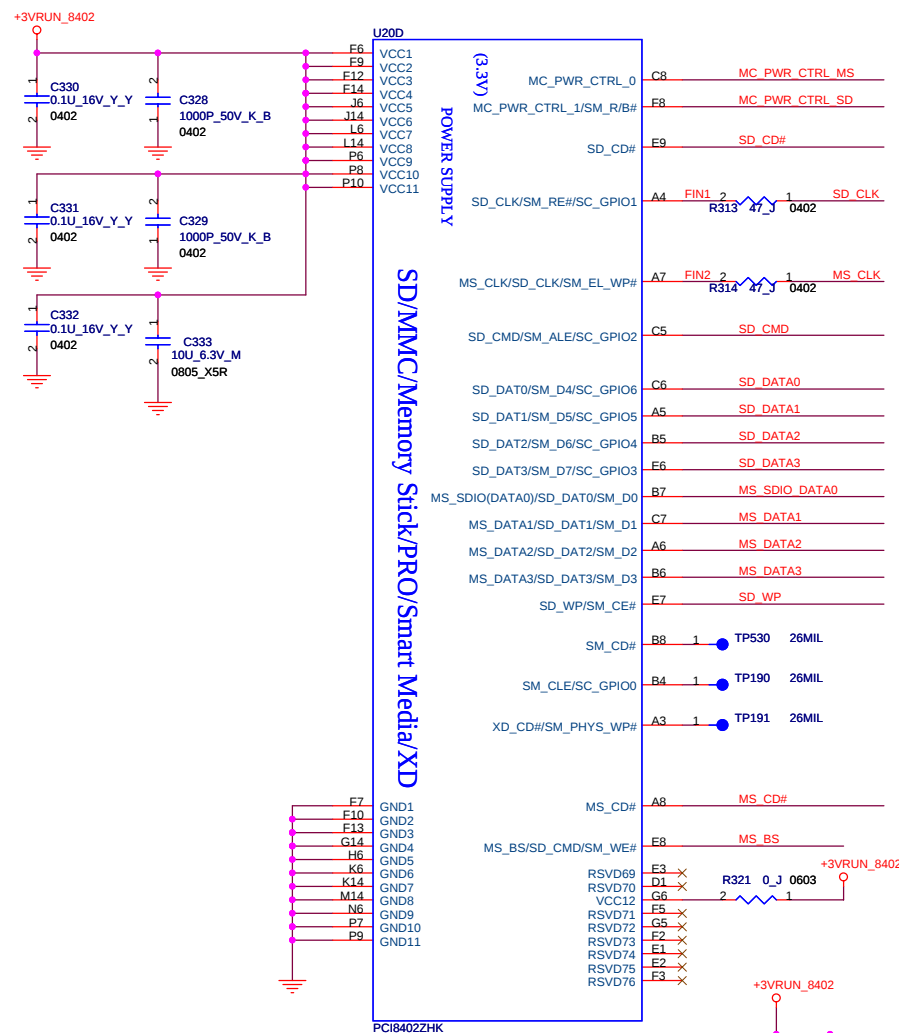


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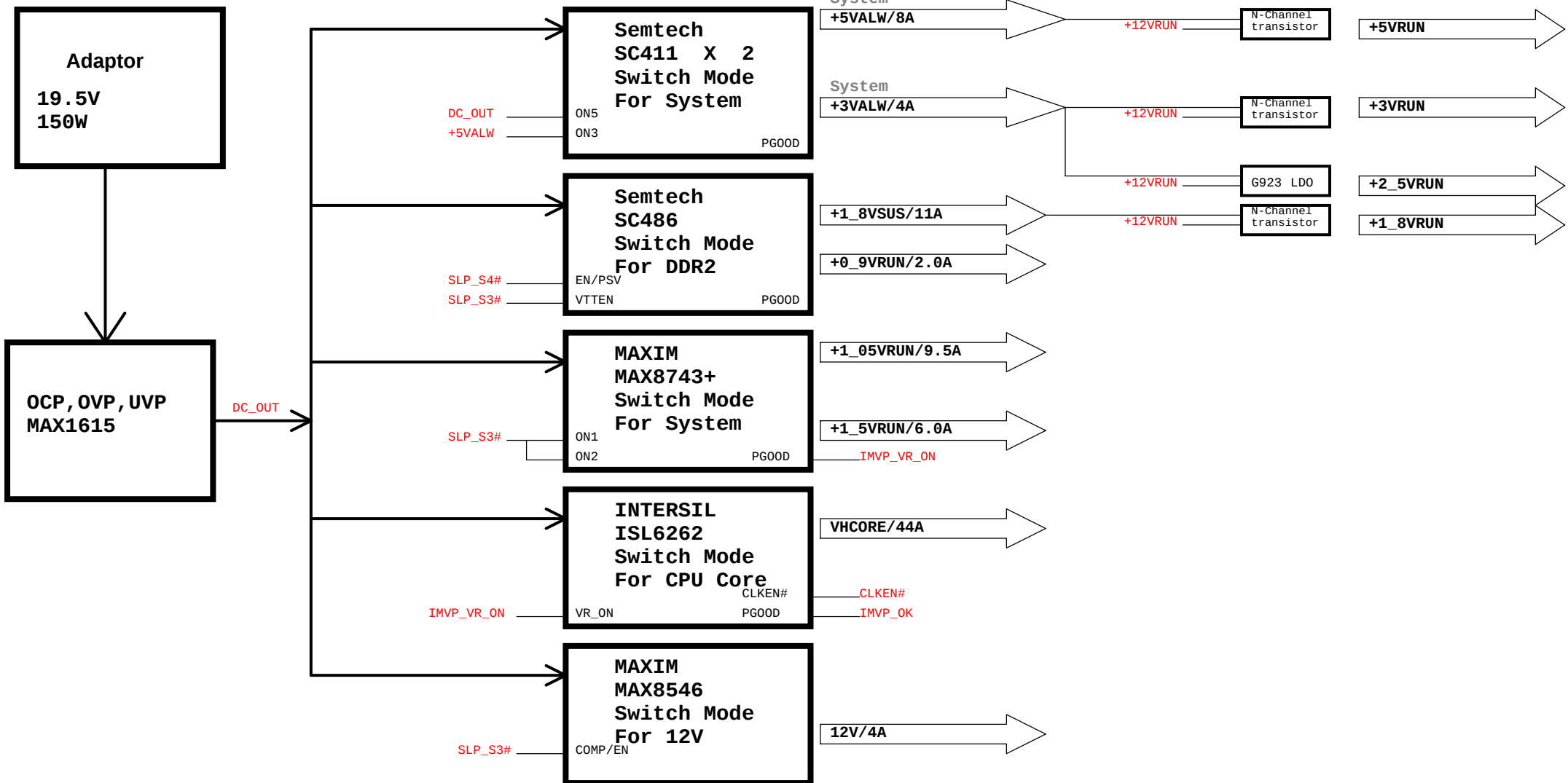
www.laptopfix.vn

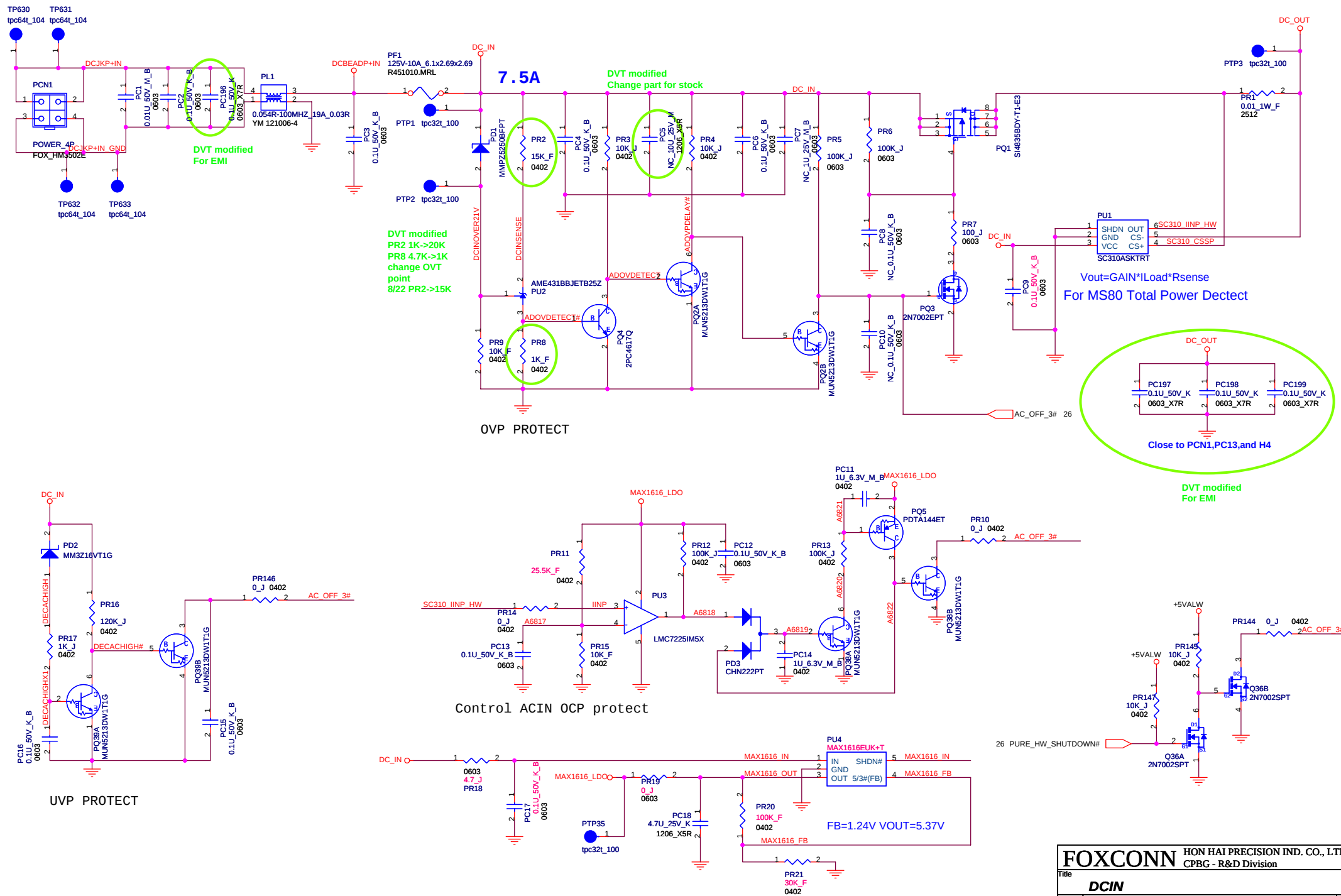


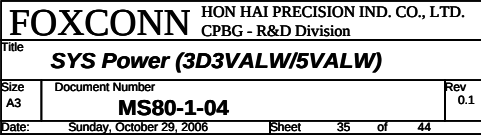




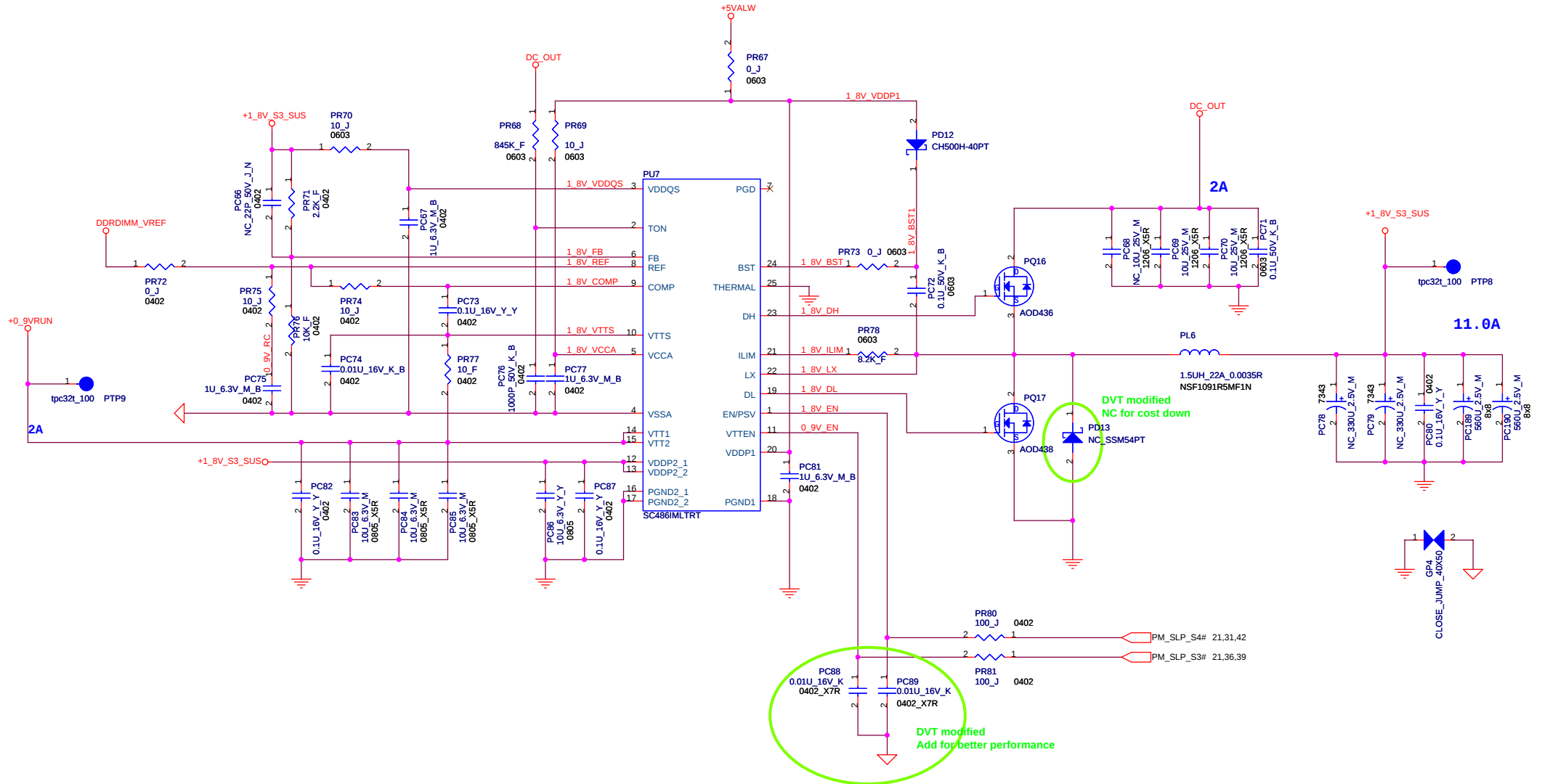


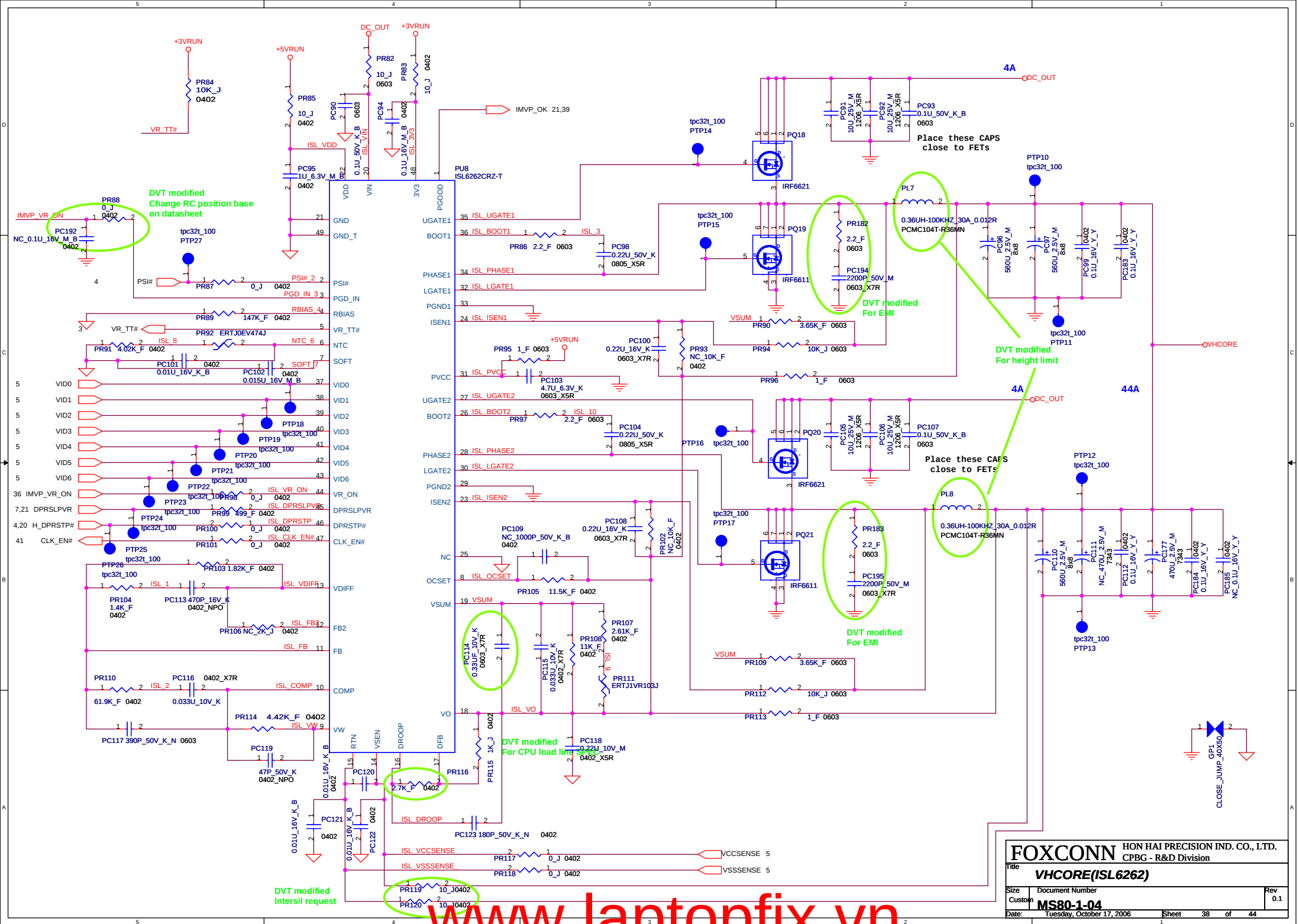


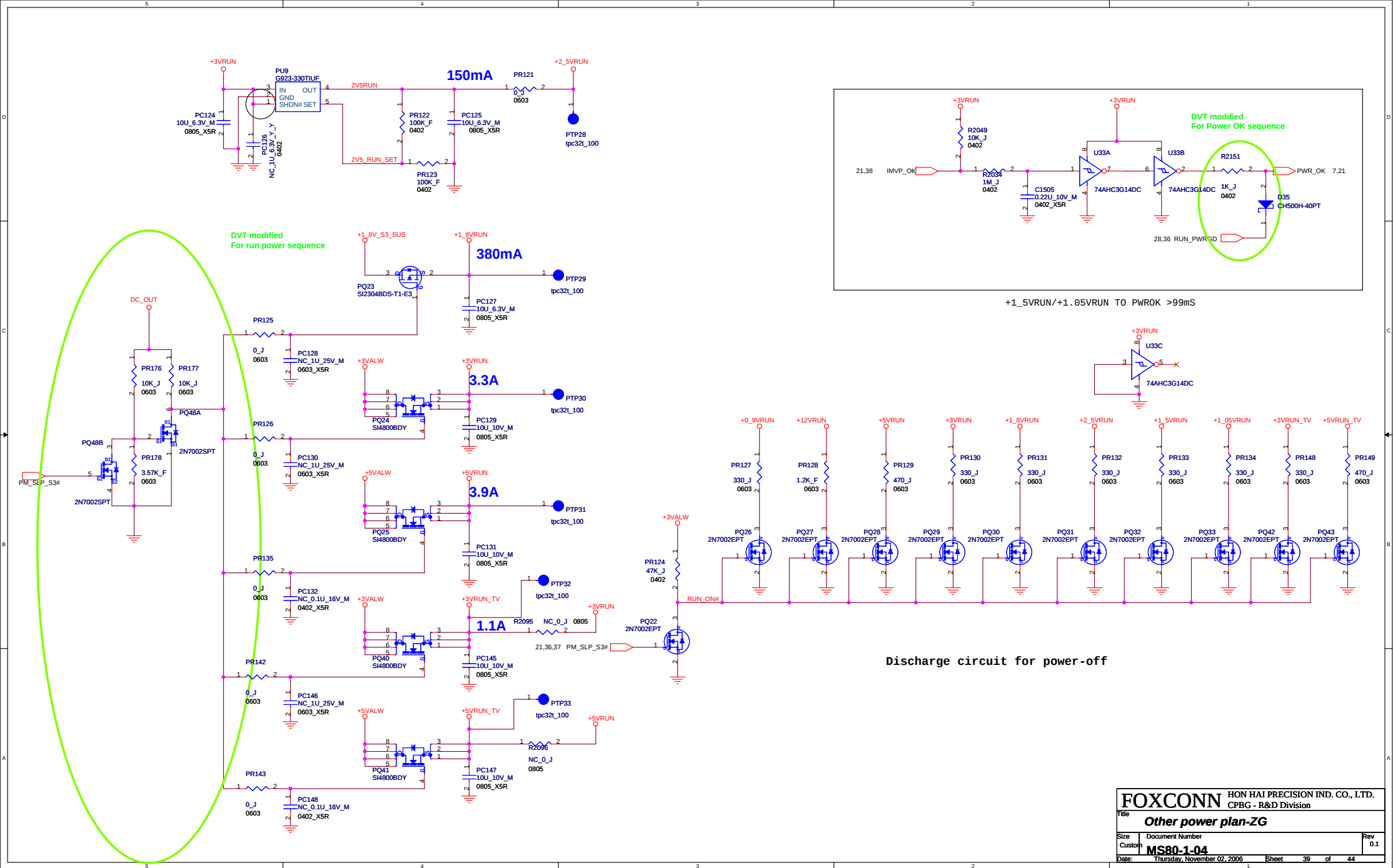














HISTORY
REV.: 0.10 (2006/07/18)

0718
P19, P21 change ODD_EJECT# from GPIO5 to GPIO10
P21 change SUSPEND_LED# from GPIO8 to GPIO25
P21 delete GPIO9 SB_RST#
P19 add GPIO17 as DDR_ALERT#

change thermal policy
P34, P3 delete PR173, Q35A, Q35B, PR171, PR172 and connect OVT_HM# to VR_TT# by adding R2087
P26, P21 add R2088, Q41, U41, C1516 and HM_SHUTDOWN_CTL(GPIO26) for thermal policy

P27 add R287, R288, R289 for TV_GND

0719
P13-15 swap DDR signals for layout]
P42 change R2052, R2053, R2082, R2083 from 0ohm to 150 ohm
P42 connect CN22, CN27 pin4 to PM_SLP_S4# for anykey wake up in S3
P42 update H4, H5, H7, H10, H11, H15 for ME
P42 change R401, R407, R406 to 100ohm
P39 change PC132, PC148 to 0.1u.16v
P39 change PR148 to 330ohm
P21 change SUSPEND_LED from GPIO 25 to GPIO27
P42 add Q42 and change U37 to 74LVC16006W for SUSPEND_LED

0720
P42 delete R2052, R2082, R2083, Q40 ;add CAP16 for ILLUMINATION_LED
P38 reserve PC177 for VHCORE
P31 change F3 to PTTC SMD1206P110TF
P26 change D19 from 1N4148 to CH500H-40PT for VF

0721

Vendor review
P17 (1)delete D21, D22, R2018 and short, change Q31 to UPA672 for avoid capacitance effect 500pf for DDC bus
(2)NC U5, U38, U39 pin3 for capacitance concern
(3)change R110, R115, R120, R122 to 390 ohm
P18 (1)R2023 changed from 1K to 3K
(2)Q33A, Q33B changed from ZN7002 to UPA672T for capacitance concern

BOM modify for common parts
P26 U41 change to 74AHC16006GW.125
P21 change Q25 to MMBT3904(SECOS)
P26 change Q28, Q39 to MMBT3904(SECOS)
P35 change PQ47 to MMBT3904(SECOS)
P40 cahnge PC139 to 3300P YAGEO
P39 change R2034 to 10M_J TA-I
P21 change R1956 to 2.2K_J 0402
P17 R2007, R2008 change to 27K_F 0603
P17 R104, R105 change to 1.82K_F 0402
P3 change R2 to 150_F
P3 update R1
P15 update R77, R78, R79, R80
P20 update R163, R161

P37 delete PR79 for duplicate with GP4
P42 change R2053 to 931_F and add R2089 for power rating
P6-12 change U2 to 12-0682945-A300

0724
P41, P18 add R2090, R2091 for 33M clk input of microp from clk gen path
P40 dummy PC134, PC143 by power team
P42 swap L38, L32, L33(mirror vertical) for Layout
P35 change PL11 to 4.7U-100KHZ 5.5A 0.04R(CVNTec)
P28 change U20A pinJ2 to High active
P42 MS/SD LED move to FIO BOARD, CN21 pin 11 change to test pad
P25 connect WLAN_SW# to CN11 pin20
P18 connect P1.3 to INT0# by customer from vendor suggestion
P26 change CN13(fan) define to pin1-4 +5VRUN, TACH, GND, PWM by thermal team9(compatible with old models)

0725
P35 change PD19, PD20 to SSM34APT and dummy PD20 by power team
P24 update CN17 symbol and vendor P/N
P42 add SW1, R2092 for RF LINK BUTTON
P21 GPIO30 connect to HARD_RST#, GPIO 31 connect to FE_RST#

0726
P17 add C1517, D21 by vendor suggestion
P19 GPIO29 connect to WLAN_SW# for TE
P42 mount CN28

0727
P21 GPIO7 connect to OVT_HM#, NC R2076 for OS shutdown
P38 dummy PC111, mount PC177 by power team
P37 change PC78, PC79 to 560U 2.5V_M (lower height parts) for layout
P35 change PC169, PC171 to 330U 6.3V_M (NEC) (lower height) for layout
P36 Add PC181 for power ripple noise (for dip caps)
P38 Add PC183, PC184, PC185 for power ripple noise (for dip caps)
P40 add PC186 for power ripple noise (for dip caps)

0728
P38 change PC108 to 0.22u.16V_K 0603 size by power team
P35 change PC155, PC159, PC160 to 330U 6.3V_M, SMD by power team(semtech)
P37 change PC78, PC70 to 330U 2.5V_M by power team(semtech)
P36 change PQ12 to IRF7904(PQ12A), change PQ14 to IRF7904(PQ12B)

0731
wlan power ldo
(1)add C1518, c1519, U42, by customer request for Intel module susceptibility to ripple noise
(2)MINI_PCIE +3.3V change to +3VRun source
wlan led
P25 add Q43, R2093 by customer for avoid LED_WLAN# abnormal behavior from wlan module
P35 remove PC160 by power team

0801
P35 add PC191 by power team(vendor suggestion)
P36 NC PR50 by power team
P38 add PC192 by power team
P35 change PR155 to 16K_F, change PR164 o 6.2K_F for ocp
P36 change PR59 to 110K_F, PR60 to 68K_F for OCP
P42 add EC7, EC8, EC9 for cpu, nb clk cross moat
P39 add R2095, R2096 for cost down
P25 (1)add R2094 for cost down,
(2)add R2097 by customer request
P17 change R2008 to 100K_J by customer

0803
P18 add R2098 by vendor suggestion
P42 change H13, H14 by ME

0804
P17 change CN29 to HS8102 cause of HS6102 not available

0816
P40 change PR140 from 140K to 143K to increase +12V voltage
P38 change PR119, PR120 from NC to 100hm for intersil request
P30 change R320, R2081 from NC to 10K, change R318 from 1M to 100K for MOR request to avoid SD/MS issue
P34 change PR2 from 1K to 20K, change PR8 from 4.7K to 1K to change OVP point
P35 change PR155 from 16K to 11K for adjusting OCP point
P36 change PR59 from 110K to 100K, change PR65 from 100K to 51K PR60 from 68K to 110K for adjusting OCP point
P40 change PQ37 from SI4892DYT to SI4890BDY for OCP
P42 add Q44 for level shift of LED_ILLUMINATION#
P40 change PD16 from SSM34APT to NC for cost down
P36 change PD10, PD11 from SSM34APT to NC for cost down
P37 change PD13 from SSM54PT to NC for cost down
P35 change PD18 from SSM34APT to NC for cost down

0817
P24 CN7 Pin49, 50->NC; Pin43, 44->GND; for ODD can not detect issue
P18 R2090->NC, C200, C202, Y1->Mount; for HDMI no audio issue
P35 PQ44, PQ45 use 2nd source as main source for stock
P36 PQ13, PQ15 use 2nd source as main source for stock

0822
P35 PR169, PR170 change to NC to change SC411 work mode to continue mode
P34 PR2 20K->15K for OVP point change

0905
P42 Add PJ2(Power SW jumper for TE request
P19 Cancel BIOS socket(U31) and add BIOS chip
P28 PC18402 GRST# signal change to PCIRST# for can not program GUID issue
P36 Change 1.5V and 1.05V timing for power good glitch issue
P21, 35 Add circuit to adjust PM_RSMRST# timing
P26 Change HW monitor power to 3VALW

0918
P35 PC176 change from 0.1u to 0.01u for Mode change to continue Add PR175(NC, 0ohm) and PC193(0.01u) for mode change
Change PC157 to 22nF and NC PC191 for better performance
P37 Add PC88, PC89 for better power performance
P38 Change PR88, PC192 position base on datasheet
Change PR116, PC114 for CPU load line SPEC
Change PL7, PL8 for height limit
P39 Change enable circuit or run power sequence
P40 Change for +12V power sequence
P36 Change PC60, PC61, add PC147 for ripple and cost down
Change PC58, PC59 for cost down
ALL input 1210 MLCC(PC5, 149, 150, 151, 163, 164, 46, 51, 49, 50, 55, 68, 69, 70, 91, 92, 105, 106, 134, 135, 136) change to 1206 with 1210 pad

0919
P31 USB power switch changed for MOR request

0921
P42 Del CAP16 and Add C1520 for height limit

0925
P19, 21, 24 Add X-BUS function on J16 connector

0926
PCN1, CN32, CN29, CN24, CN25, CN13, CN28, CN31, CN22 Add test point
P25 Modified WLAN connector and terminator type for mechanical
P16 CN3 change D-SUB conn color for ME requirement
P32 CN25 change RJ45 conn color for ME requirement
P24 CN32 change to HM4202E-DW for ME requirement

0927
P27 CN24 change to SCN553S86TNW01A6 for ME requirement

0928
H2, H7, H13, H15, H20 change screw hole footprint for ME requirement

1002
P37 PC88 pin2 and PC89 pin2 change connection to GND_SC486 in order to improve 1.8V unstable for power requirement.
P38 Remove PR182, PR183, PR184, PR185 to release layout space.
P41 Change CLK_PCIE_MINI damping resistor from 33ohm to 22ohm for signal quality improvement.

1004
P17 Modify for sil1390 and sil1392 co-design.
P18 Add R2138, R2139, R2140, R2141 to connect I2C bus for FAE recommended.
P39 U33 change to Schmitt trigger part for MOR requirement.
P40 Remove PR179, PR180, add 12V_EN for power requirement.
P40 Del MAX8546_DC net and connect DC_OUT for PU10 VIN.

1005
P17 Modified Sil139X circuit
P21 Add D35 on PowerOK signal for ICH sequence timing

1009
P17 Modified Sil139X circuit
P34 Add PC196, 197, 198, 199 for EMI
P38 Add PR182, PR183 PC194, PC195 for EMI

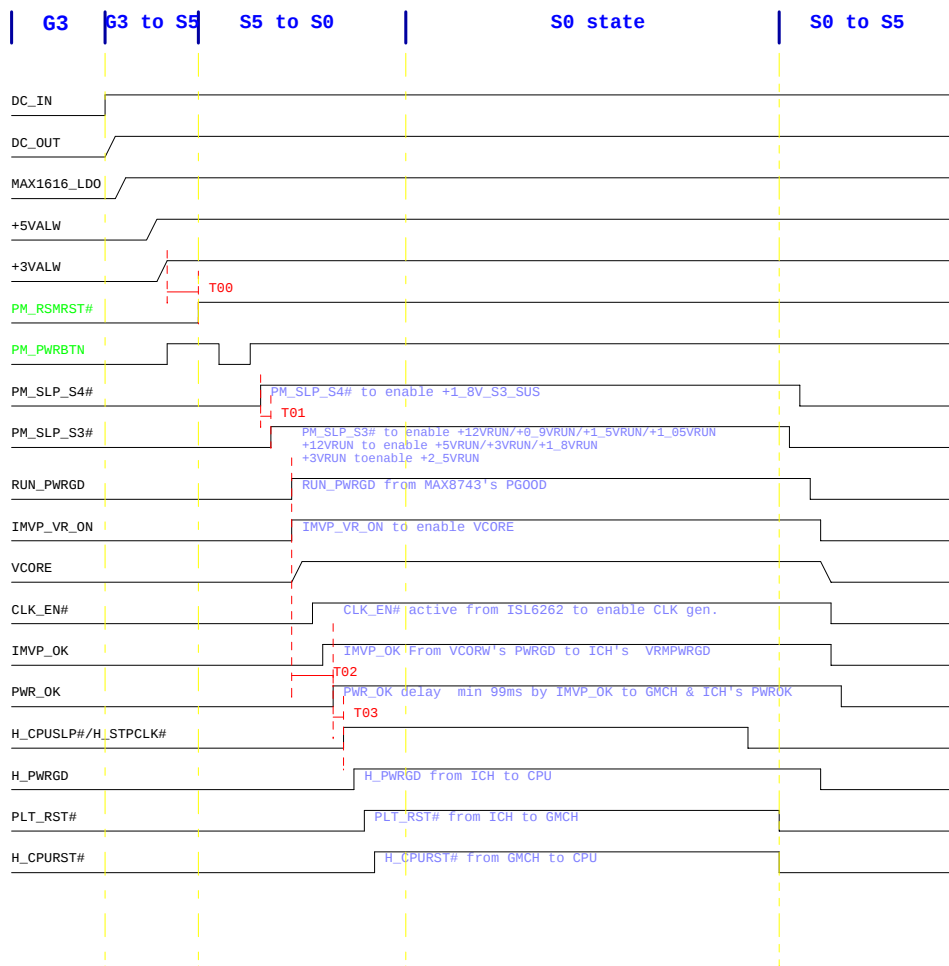
1010
P24 ODD CONN(CN7)change to FFC and pin swaped for ME
P30 Front IO board CONN(CN7)change type for ME request
C335, 336, 341, 342 change to NC for MOR request

1011
P34 Change DC_IN test point size

1013
P16 CRT CONN(CN3) pin10 connect to GND according to SONY SPEC
P27 C412 change from 100p to 470p for MOR request
P30 R323 change to 100K for MOR request
P31 Remove USB power fuse for MOR request
P39 Add R2151 for PWR_OK sequence

MS80 Power On Sequence Timing

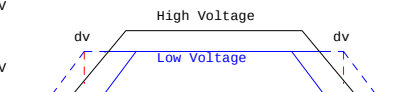
Version : 0.0
Modified date : 8/11/2006



T00 : (Min 10ms) ALW power supply to PM_RSMRST# at least 10ms (Please refer to ICH7 EDS of t204 timing)
T01 : (1 - 2 RTCCCLK) PM_SLP4# to PM_SLP3# (Please refer to ICH7 EDS of t234 timing)
T02 : (Min 99ms) RUN_PWRGD to IMVP_OK (Please refer to ICH7 EDS of t214 timing)
T03 : (Max 50ns) PWR_OK active to H_CPUSLP# and H_STPCLK#

Remark: (Item1,2,3 add Diode; Item4,5,6 add discharge circuit; Item7 for implement TV)
SPEC please refer to Intel 16981 15.4 GMCH/ICH7M Platform Power -up Requirements)

1. V5REF(+5VRUN) -> +3VRUN, dt:0.7mV
2. V5REF_SUS(+5VALW) -> +3VALW, dt:0.7mV
3. +2.5VRUN -> GMCH_VCC(1.05V), dt:0.7mV
4. +1.5VRUN -> +GMCH(1.05V), dt:0.7mV
5. +3.3VRUN -> +2.5VRUN, dt:0.3mV
6. +3.3VRUN -> +5VRUN (VccLAN), dt:0.3mV
7. +3.3VRUN -> +1.5VRUN(TV), dt:0.7mV



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